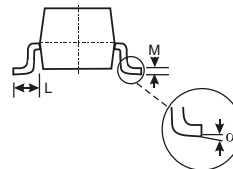
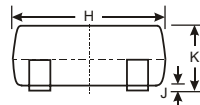
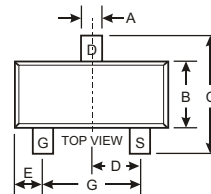


Features

- Super high density cell design for extremely low $R_{DS(ON)}$.
- Exceptional on-resistance and maximum DC current capability.
- We declare that the material of product compliance with RoHS requirements.



| SOT-23 | | |
|----------------------|-------|-------|
| Dim | Min | Max |
| A | 0.37 | 0.51 |
| B | 1.20 | 1.40 |
| C | 2.30 | 2.50 |
| D | 0.89 | 1.03 |
| E | 0.45 | 0.60 |
| G | 1.78 | 2.05 |
| H | 2.80 | 3.00 |
| J | 0.013 | 0.10 |
| K | 0.903 | 1.10 |
| L | 0.45 | 0.61 |
| M | 0.085 | 0.180 |
| α | 0° | 8° |
| All Dimensions in mm | | |

APPLICATIONS

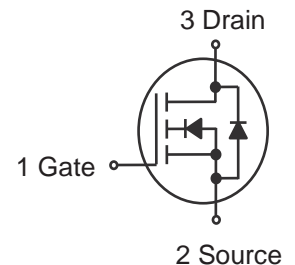
- Power Management in Notebook.
- Portable equipment.
- Battery powered system.
- Load switch.
- Marking Code:2302.

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

| Parameter | Symbol | Value | Unit |
|---|-----------------|---------------|--------------------|
| Drain-Source Voltage | V_{DS} | 20 | V |
| Gate-Source Voltage | V_{GS} | ± 8 | V |
| Drain Current | I_D | 2.4 | A |
| Peak Drain Current ¹⁾ | I_{DM} | 10 | A |
| Power Dissipation $T_A = 25^\circ\text{C}$ $T_A = 75^\circ\text{C}$ | P_{tot} | 0.9 0.57 | W |
| Thermal Resistance from Junction to Ambient (PCB mounted) ²⁾ | $R_{\theta JA}$ | 140 | $^\circ\text{C/W}$ |
| Junction Temperature | T_J | 150 | $^\circ\text{C}$ |
| Storage Temperature Range | T_{stg} | - 55 to + 150 | $^\circ\text{C}$ |

¹⁾ Repetitive Rating: Pulse width limited by the Maximum junction temperature.

²⁾ 1 in² 2oz Cu PCB board.



Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

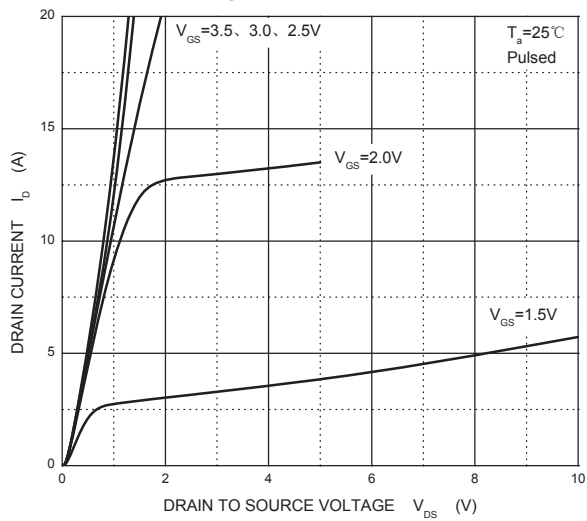
| Parameter | Symbol | Test Condition | Min | Typ | Max | Units |
|---|---------------|--|------|-------|-----------|----------|
| Static | | | | | | |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = 10\mu A$ | 20 | | | V |
| Gate-threshold voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 50\mu A$ | 0.65 | 0.95 | 1.2 | |
| Gate-body leakage | I_{GSS} | $V_{DS} = 0V, V_{GS} = \pm 8V$ | | | ± 100 | nA |
| Zero gate voltage drain current | I_{DSS} | $V_{DS} = 20V, V_{GS} = 0V$ | | | 1 | μA |
| Drain-source on-resistance ^a | $r_{DS(on)}$ | $V_{GS} = 4.5V, I_D = 3.6A$ | | 0.035 | 0.060 | Ω |
| | | $V_{GS} = 2.5V, I_D = 3.1A$ | | 0.045 | 0.115 | |
| Forward transconductance ^a | g_{fs} | $V_{DS} = 5V, I_D = 3.6A$ | | 8 | | S |
| Diode forward voltage | V_{SD} | $I_S = 0.94A, V_{GS} = 0V$ | | 0.76 | 1.2 | V |
| Dynamic | | | | | | |
| Total gate charge | Q_g | $V_{DS} = 10V, V_{GS} = 4.5V, I_D = 3.6A$ | | 4.0 | | nC |
| Gate-source charge | Q_{gs} | | | 0.65 | | |
| Gate-drain charge | Q_{gd} | | | 1.5 | | |
| Input capacitance ^b | C_{iss} | $V_{DS} = 10V, V_{GS} = 0V, f = 1MHz$ | | 300 | | pF |
| Output capacitance ^b | C_{oss} | | | 120 | | |
| Reverse transfer capacitance ^b | C_{rss} | | | 80 | | |
| Switching ^b | | | | | | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD} = 10V,$ $R_L = 5.5\Omega, I_D \approx 3.6A,$ $V_{GEN} = 4.5V, R_g = 6\Omega$ | | 7 | 15 | ns |
| Rise time | t_r | | | 55 | 8 | |
| Turn-off delay time | $t_{d(off)}$ | | | 16 | 6 | |
| Fall time | t_f | | | 10 | 2 | |

Notes :

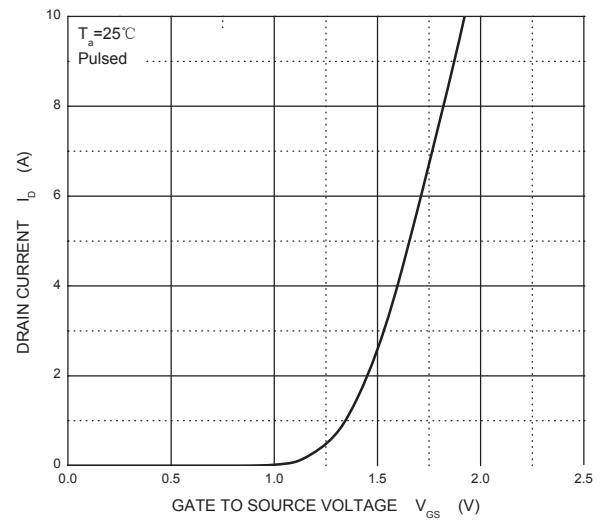
- Pulse Test : Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- These parameters have no way to verify.

TYPICAL TRANSIENT CHARACTERISTICS

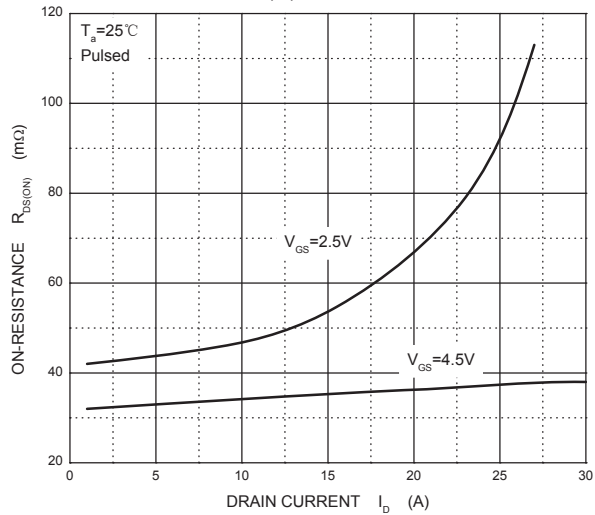
Output Characteristics



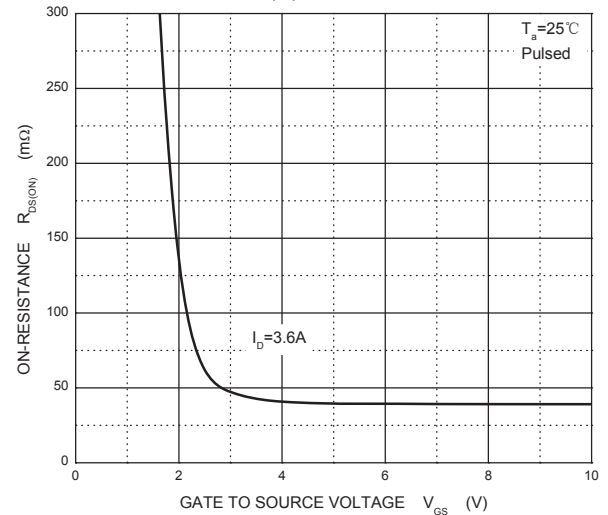
Transfer Characteristics



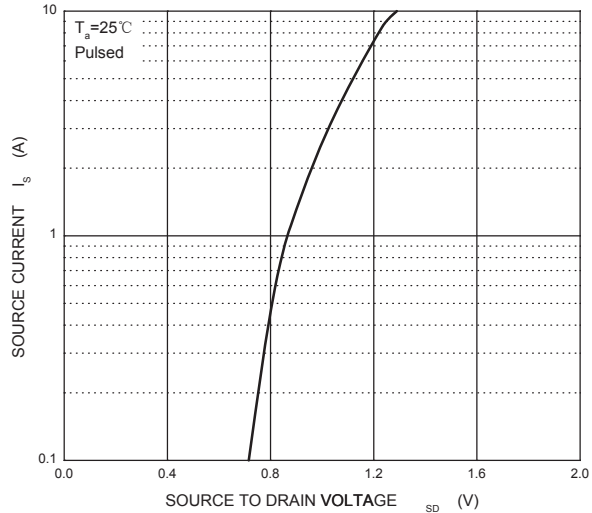
$R_{DS(ON)}$ — I_D



$R_{DS(ON)}$ — V_{GS}



I_S — V_{SD}



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